

Packaging Convention - 22 & 23 August

Scion, Te Papa Tipu Innovation Park, 49 Sala Street, Rotorua, New Zealand

Day one

22 August
10.00am - 4.30pm

Global packaging trends and technologies

- Disruptive sustainable packaging trends.
Speaker: Lou Sherman, Scion
- Printed and hybrid manufacturing for intelligent packaging applications.
Speaker: Maria Smolander, VTT (Finland)
- Making the internet of everything environmentally sustainable, and printable: Printed energy harvesting, storage and circuits for distributed smart objects.
Speaker: Donald Lupo, TUT (Finland)
- Advanced plastic material characterisation.
Speaker: Marc Gaugler, Scion
- Corrugated box performance in chilled supply chains.
Speaker: Kelly Wade, Scion

Interactive tour of Scion

- Bioplastics and extrusion
- Printed electronics
- Compostability standards and testing
- Paper and board performance under controlled environment (e.g. temperature/humidity)
- Global food contact trends

Wrap up session

Packaging of the future: Opportunities and challenges.
Speaker: TBC



Day two

23 August
9.00am - 3.00pm



New Zealand | China
FOOD PROTECTION NETWORK
新西兰中国食品保证交流网

Guest speakers from China

- IoT system for cross-border food traceability.
Speaker: Professor Junyu Wang, Fundan University
- Paperboard packaging advancement in China.
Speaker: Professor Hong bin Liu, Tianjin University
- The status of biodegradable and biobased plastic in China.
Speaker: Professor Yunxuan Weng, Beijing Technology & Business University

Presentations from New Zealand network partners

- Combining design and engineering thinking to develop creative packaging solutions.
Speaker: Eli Gray-Stuart, Massey University
- Using starch for food package.
Speaker: Fan Zhu, UoA
- Active and intelligent packaging: enhancing and monitoring quality.
Speaker: Keith Sharrock, Plant & Food Research
- Bionanotechnology for active packaging.
Speaker: Craig Billington, ESR
- Advanced IOT technologies for packaging.
Speaker: Hong Zhang, Ag Research
- Consumer perceptions of smart packaging technologies
Speaker: Miranda Miroso, Otago University

Any questions, please contact Lou Sherman at lou.sherman@scionresearch.com or 07 343 5503

Register via <https://packaging-convention.lilregie.com/>

